

SHOULDER

SHOULDER ELECTRONICS CO., LTD

SPECIFICATION FOR APPROVAL

NO 编号: _____

CUSTOMER 客 户: _____

PRODUCT 产 品: _____ SAW FILTER _____

MODEL NO 型 号: _____ HDF447.725M F11 _____

PREPARED 编 制: _____ Fengyu _____ CHECKED 审 核: _____ York _____

APPROVED 批 准: _____ Lijiating _____ DATE 日 期: _____ 2006-5-11 _____

CUSTOMER 客户确认意见:

CHECKED 审 核:

APPROVED 批 准:

DATE 日 期:

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1.SCOPE

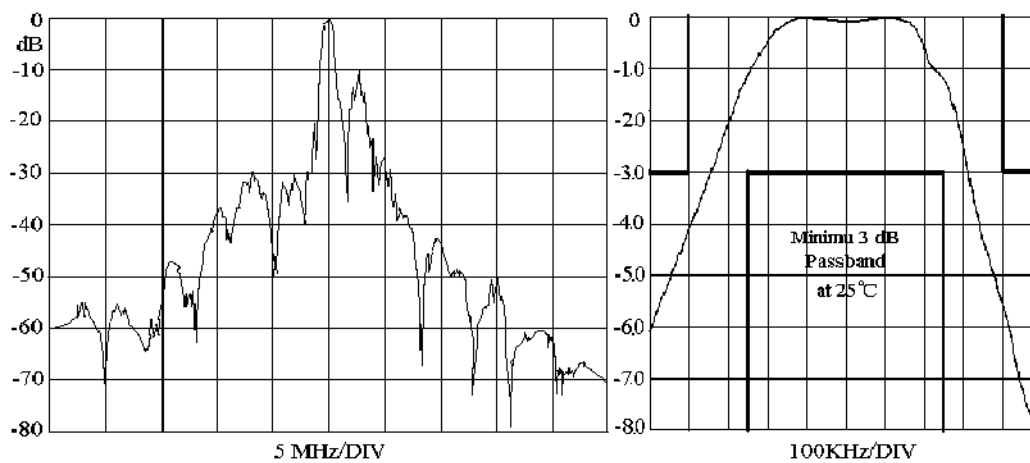
This specification shall cover the characteristics of SAW filter With 447.725MHz used for remote-control security.

2. ELECTRICAL SPECIFICATION

DC Voltage VDC	10V
AC Voltage Vpp	10V50Hz/60Hz
Storage temperature	-45°C to +85°C
RF Power Dissipation	0dBm

Electronic Characteristics

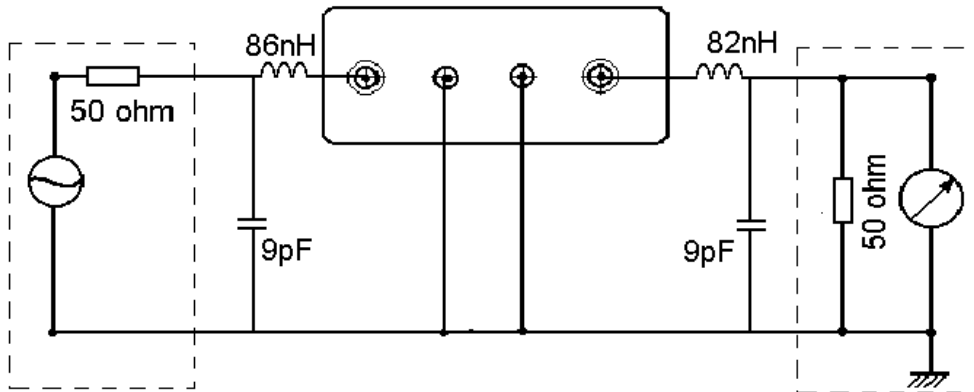
2-1.Type frequency response



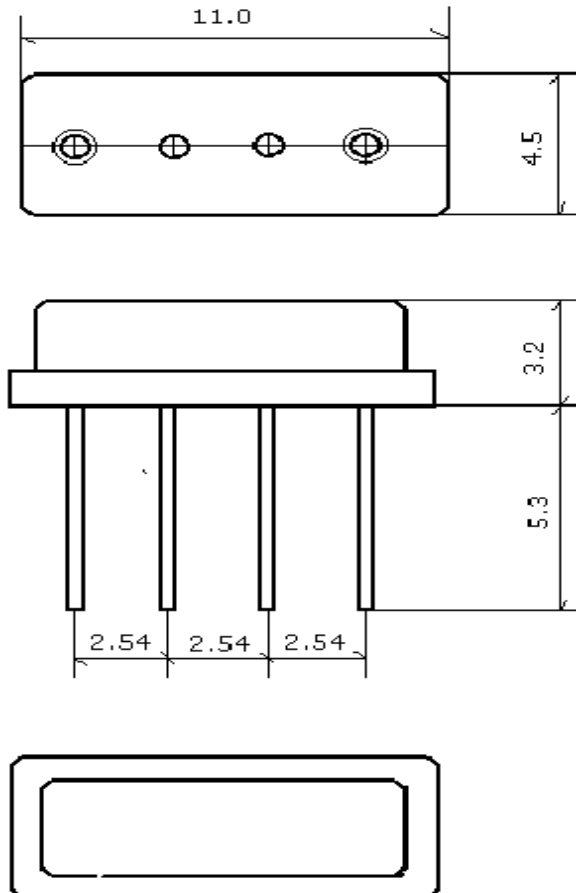
2-2.Electrical characteristics

Characteristics		Sym	Notes	Min.	Typical	Max.	Units
Center Frequency	Absolute Frequency	Fc	1.2	447.650	447.725	447.800	M Hz
	tolerance from Nominal	Δfc				± 80	KHz
Insertion Loss		IL	1		1.7	3.0	dB
3dB Bandwidth		BW ₃	1.2	500	700	800	KHz
Rejection	At fo-21.4MHz (Image)		1	40	50		dB
	At fo-10.7 MHz (LO)			16	40		
	Ultimate				80		
Temperature characteristics	Operating case temp.	Tc	3.4	-35		+85	°C
	Tumover temp.	To		22	37	62	°C
	Tumover Frequency	fo			fc		MHz
	Freq.temp.coefficient	FTC			0.032		ppm/°C
Frequency aging			5		< ± 10		ppm/y

3. TEST CIRCUIT



4. DIMENSION



5. ENVIRONMENTAL CHARACTERISTICS

5-1 High temperature exposure

Subject the device to +85°C for 16 hours. Then release the filter into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in table 1.

5-2 Low temperature exposure

Subject the device to -20°C for 16 hours. Then release the device into the room conditions for 24 hours prior to the measurement. It shall fulfill the specifications in table 1.

5-3 Temperature cycling

Subject the device to a low temperature of -40°C for 30 minutes. Following by a high temperature of $+80^{\circ}\text{C}$ for 30 Minutes. Then release the device into the room conditions for 24 hours prior to the measurement. It shall meet the specifications in table 1.

5-4 Resistance to solder heat

Dip the device terminals no closer than 1.5mm into the solder bath at $260^{\circ}\text{C} \pm 10^{\circ}\text{C}$ for 10 ± 1 sec. Then release the device into the room conditions for 4 hours. The device shall meet the specifications in table 1.

5-5 Solderability

Subject the device terminals into the solder bath at $245^{\circ}\text{C} \pm 5^{\circ}\text{C}$ for 5s, More than 95% area of the terminals must be covered with new solder. It shall meet the specifications in table 1.

5-6 Mechanical shock

Drop the device randomly onto the concrete floor from the height of 1m 3 times. the device shall fulfill the specifications in table 1.

5-7 Vibration

Subject the device to the vibration for 1 hour each in x,y and z axes with the amplitude of 1.5 mm at 10 to 55 Hz. The device shall fulfill the specifications in table 1.

5-8 Lead fatigue

5-8-1 Pulling test

Weight along with the direction of lead without an shock 1kg. The device shall satisfy all the initial Characteristics.

5-8-2 Bending test

Lead shall be subject to withstand against 90°C bending with 450g weight in the direction of thickness. This operation shall be done toward both direction. The device shall show no evidence of damage and shall satisfy all the initial electrical characteristics.

6. REMARK

6.1 Static voltage

Static voltage between signal load & ground may cause deterioration & destruction of the component. Please avoid static voltage.

6.2 Ultrasonic cleaning

Ultrasonic vibration may cause deterioration & destruction of the component. Please avoid ultrasonic cleaning

6.3 Soldering

Only leads of component may be soldered. Please avoid soldering another part of component.